



## Material Content Data Sheet



<b>Sales Product Name</b>		SPD15P10P G		<b>Issued</b>		20. July 2018		
<b>MA#</b>		MA000442434						
<b>Package</b>		PG-TO252-3-311		<b>Weight*</b>		315.91 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	3.612	1.14	1.14	11435	11435
leadframe	non noble metal	iron	7439-89-6	0.143	0.05		454	
	inorganic material	phosphorus	7723-14-0	0.043	0.01		136	
	non noble metal	copper	7440-50-8	143.098	45.29	45.35	452964	453554
wire	non noble metal	aluminium	7429-90-5	10.726	3.40	3.40	33953	33953
encapsulation	inorganic material	antimonytrioxide	1309-64-4	1.852	0.59		5862	
	plastics	brominated resin	-	1.984	0.63		6280	
	organic material	carbon black	1333-86-4	2.116	0.67		6699	
	plastics	epoxy resin	-	17.856	5.65		56522	
	inorganic material	silicondioxide	60676-86-0	108.460	34.33	41.87	343320	418683
leadfinish	non noble metal	tin	7440-31-5	3.787	1.20	1.20	11987	11987
plating	non noble metal	nickel	7440-02-0	0.086	0.03		274	
	inorganic material	phosphorus	7723-14-0	0.000	0.00	0.03	1	275
solder	noble metal	silver	7440-22-4	0.074	0.02		233	
	non noble metal	tin	7440-31-5	0.059	0.02		187	
	non noble metal	lead	7439-92-1	2.814	0.89	0.93	8909	9329
heatspreader	non noble metal	iron	7439-89-6	0.019	0.01		61	
	inorganic material	phosphorus	7723-14-0	0.006	0.00		18	
	non noble metal	copper	7440-50-8	19.177	6.07	6.08	60705	60784
*deviation	< 10%		Sum in total:			100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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